

EVLYS LTD. - POWER SEMICONDUCTORS DEVICES -
Wholesale and Retail.

Phase Control Disc Thyristor Type DT40-500-24

High power cycling capability / Low on-state and switching losses
 Designed for traction and industrial applications

Mean on-state current	I _{TAV}	500 A
Repetitive peak off-state voltage	V _{DRM}	2000 ÷ 2400 V
Repetitive peak reverse voltage	V _{RRM}	
Turn-off time	t _q	250, 320, 400, 500 µs
V _{DRM} , V _{RRM} , V	2000	2200
Voltage code	20	22
T _j , °C		-60 ÷ 125

MAXIMUM ALLOWABLE RATINGS

Symbols and parameters		Units	Values	Test conditions	
ON-STATE					
I _{TAV}	Mean on-state current	A	500 647	T _c =97 °C, Double side cooled T _c =85 °C, Double side cooled 180° half-sine wave; 50 Hz	
I _{TRMS}	RMS on-state current	A	785	T _c =97 °C, Double side cooled 180° half-sine wave; 50 Hz	
I _{TSM}	Surge on-state current	kA	12.5 14.0	T _j =T _j ^{max} T _j =25 °C	180° half-sine wave; t _p =10 ms; single pulse; V _D =V _R =0 V; Gate pulse: I _G =2 A; t _{GP} =50 µs; di _G /dt≥1 A/µs
			13.0 15.0	T _j =T _j ^{max} T _j =25 °C	180° half-sine wave; t _p =8.3 ms; single pulse; V _D =V _R =0 V; Gate pulse: I _G =2 A; t _{GP} =50 µs; di _G /dt≥1 A/µs
I ² t	Safety factor	A ² ·10 ³	780 980	T _j =T _j ^{max} T _j =25 °C	180° half-sine wave; t _p =10 ms; single pulse; V _D =V _R =0 V; Gate pulse: I _G =2 A; t _{GP} =50 µs; di _G /dt≥1 A/µs
			700 930	T _j =T _j ^{max} T _j =25 °C	180° half-sine wave; t _p =8.3 ms; single pulse; V _D =V _R =0 V; Gate pulse: I _G =2 A; t _{GP} =50 µs; di _G /dt≥1 A/µs
BLOCKING					
V _{DRM} , V _{RRM}	Repetitive peak off-state and Repetitive peak reverse voltages	V	2000÷2400	T _{j min} < T _j <T _{j max} ; 180° half-sine wave; 50 Hz; Gate open	
V _{DSM} , V _{RSM}	Non-repetitive peak off-state and Non-repetitive peak reverse voltages	V	2100÷2500	T _{j min} < T _j <T _{j max} ; 180° half-sine wave; single pulse; Gate open	
V _D , V _R	Direct off-state and Direct reverse voltages	V	0.6·V _{DRM} 0.6·V _{RRM}	T _j =T _j ^{max} ; Gate open	

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TRIGGERING				
I_{FGM}	Peak forward gate current	A	8	$T_j = T_{j \max}$
V_{RGM}	Peak reverse gate voltage	V	5	
P_G	Gate power dissipation	W	4	$T_j = T_{j \max}$ for DC gate current
SWITCHING				
$(di_T/dt)_{crit}$	Critical rate of rise of on-state current non-repetitive ($f=1$ Hz)	A/ μ s	1600	$T_j = T_{j \max}; V_D = 0.67 \cdot V_{DRM}; I_{TM} = 2100$ A; Gate pulse: $I_G = 2$ A; $t_{GP} = 50 \mu$ s; $di_G/dt \geq 2$ A/ μ s
THERMAL				
T_{stg}	Storage temperature	°C	-60÷50	
T_j	Operating junction temperature	°C	-60÷125	
MECHANICAL				
F	Mounting force	kN	14.0÷16.0	
a	Acceleration	m/s ²	50	Device clamped

CHARACTERISTICS

Symbols and parameters		Units	Values	Conditions
ON-STATE				
V_{TM}	Peak on-state voltage, max	V	1.85	$T_j = 25$ °C; $I_{TM} = 1570$ A
$V_{T(TO)}$	On-state threshold voltage, max	V	1.068	$T_j = T_{j \max};$
r_T	On-state slope resistance, max	$m\Omega$	0.626	$0.5 \pi I_{TAV} < I_T < 1.5 \pi I_{TAV}$
I_L	Latching current, max	mA	1000	$T_j = 25$ °C; $V_D = 12$ V; Gate pulse: $I_G = 2$ A; $t_{GP} = 50 \mu$ s; $di_G/dt \geq 1$ A/ μ s
I_H	Holding current, max	mA	300	$T_j = 25$ °C; $V_D = 12$ V; Gate open
BLOCKING				
I_{DRM}, I_{RRM}	Repetitive peak off-state and Repetitive peak reverse currents, max	mA	100	$T_j = T_{j \max};$ $V_D = V_{DRM}; V_R = V_{RRM}$
$(dv_D/dt)_{crit}$	Critical rate of rise of off-state voltage ¹⁾ , min	V/ μ s	200, 320, 500, 1000, 1600, 2000, 2500	$T_j = T_{j \max};$ $V_D = 0.67 \cdot V_{DRM}$; Gate open
TRIGGERING				
V_{GT}	Gate trigger direct voltage, max	V	3.00 2.50 1.50	$T_j = T_{j \min}$ $T_j = 25$ °C $T_j = T_{j \max}$
I_{GT}	Gate trigger direct current, max	mA	500 300 150	$T_j = T_{j \min}$ $T_j = 25$ °C $T_j = T_{j \max}$
V_{GD}	Gate non-trigger direct voltage, min	V	0.55	$T_j = T_{j \max};$
I_{GD}	Gate non-trigger direct current, min	mA	60.00	$V_D = 0.67 \cdot V_{DRM};$ Direct gate current
SWITCHING				
t_{qd}	Delay time, max	μ s	1.25	$T_j = 25$ °C; $V_D = 1000$ V; $I_{TM} = I_{TAV};$ $di/dt = 200$ A/ μ s;
t_{gt}	Turn-on time, max	μ s	8.00	Gate pulse: $I_G = 2$ A; $V_G = 20$ V; $t_{GP} = 50 \mu$ s; $di_G/dt = 2$ A/ μ s
t_q	Turn-off time ²⁾ , max	μ s	250, 320, 400, 500	$dv_D/dt = 50$ V/ μ s; $T_j = T_{j \max}; I_{TM} = I_{TAV};$ $di_R/dt = -10$ A/ μ s; $V_R = 100$ V; $V_D = 0.67 \cdot V_{DRM}$
Q_{rr}	Total recovered charge, max	μ C	1580	$T_j = T_{j \max}; I_{TM} = 500$ A;
t_{rr}	Reverse recovery time, max	μ s	24	$di_R/dt = -10$ A/ μ s;
I_{rrM}	Peak reverse recovery current, max	A	132	$V_R = 100$ V

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THERMAL					
R_{thjc}	Thermal resistance, junction to case, max	$^{\circ}\text{C}/\text{W}$	0.030	Direct current	Double side cooled
R_{thjc-A}			0.066		Anode side cooled
R_{thjc-K}			0.054		Cathode side cooled
R_{thck}	Thermal resistance, case to heatsink, max	$^{\circ}\text{C}/\text{W}$	0.006	Direct current	
MECHANICAL					
W	Weight, max	g	210		
D_s	Surface creepage distance	mm (inch)	7.86 (0.309)		
D_a	Air strike distance	mm (inch)	6.10 (0.240)		

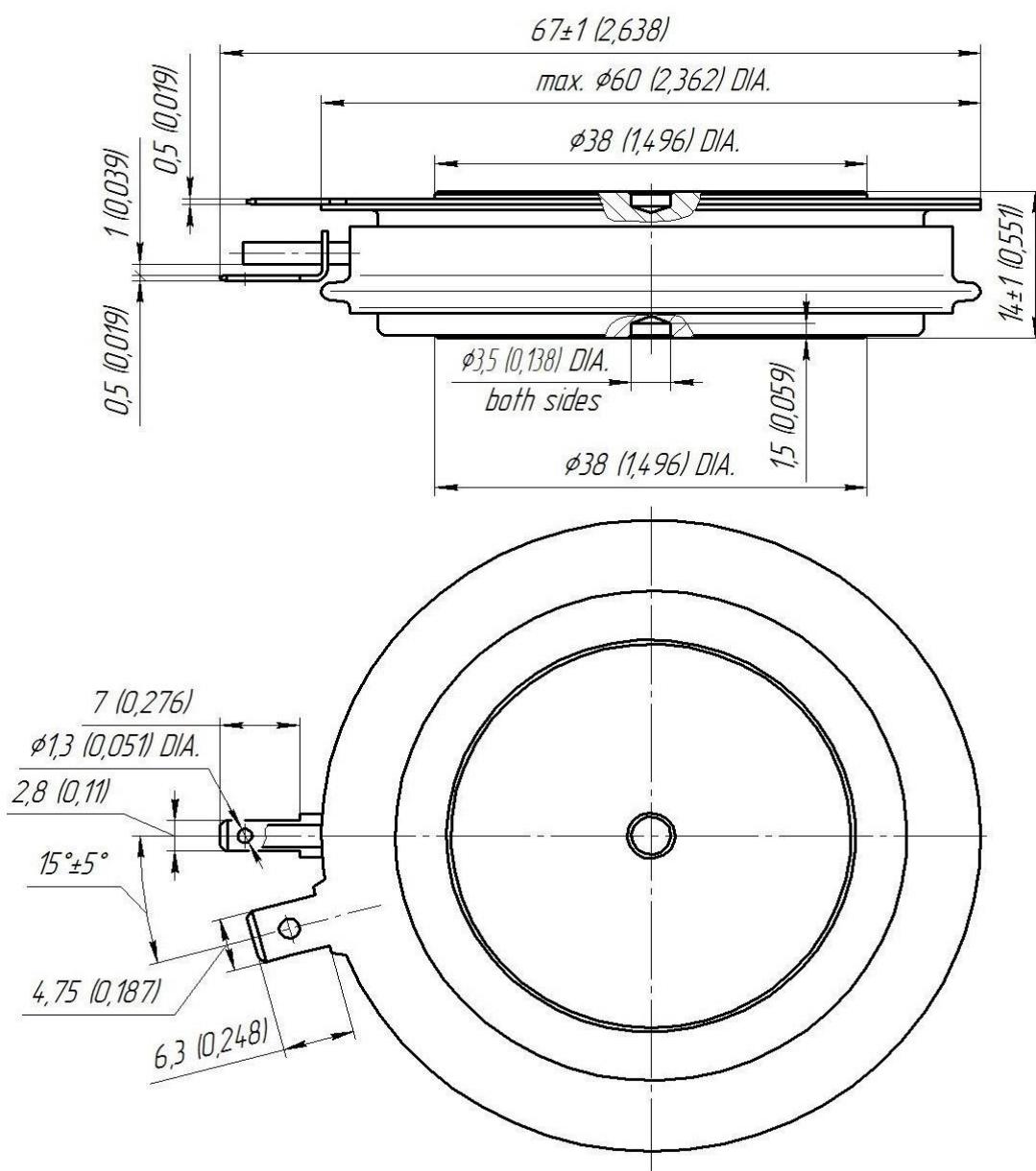
PART NUMBERING GUIDE						NOTES						
DT	40	500	24	7	2							
1	2	3	4	5	6							
1. DT - Phase Control Disc Thyristor												
2. Element Diameter												
3. Mean on-state current, A												
4. Voltage code												
5. Critical rate of rise of on-state current non-repetitive, V/ μs												
6. Turn-off time ($\text{dv}_D/\text{dt}=50 \text{ V}/\mu\text{s}$)												
						1) Critical rate of rise of off-state voltage						
						Symbol of Group $(\text{dv}_D/\text{dt})_{\text{crit}, \text{V}/\mu\text{s}}$	4	5	6	7	8	8.5
						200	320	500	1000	1600	2000	2500
						2) Turn-off time ($\text{dv}_D/\text{dt}=50 \text{ V}/\mu\text{s}$)						
						Symbol of Group $t_{\text{off}}, \mu\text{s}$	0	0	0	0	0	
						250	320	400	400	500		

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OVERALL DIMENSIONS

Package type: T.C1



All dimensions in millimeters (inches)